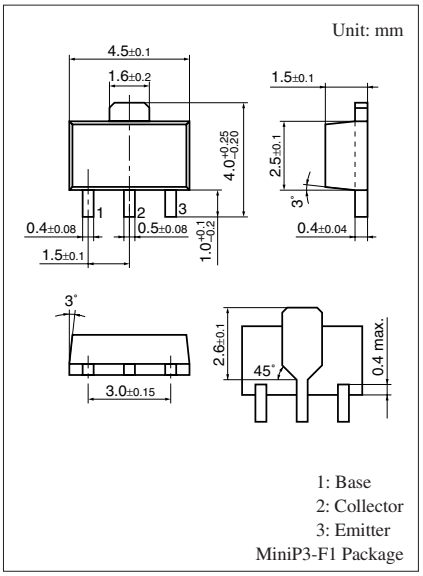
2SD2441

Silicon NPN epitaxial planar type

For low-frequency output amplification



Marking Symbol: 1V

■ Features

- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	10	V
Collector-emitter voltage (Base open)	V_{CEO}	10	V
Emitter-base voltage (Collector open)	V_{EBO}	7	V
Collector current	I_C	1.5	A
Peak collector current	I_{CP}	2	A
Collector power dissipation *	P_C	1	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

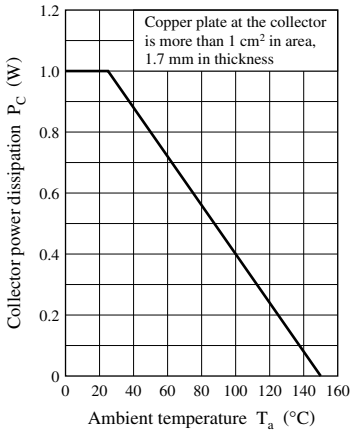
Note) ∗: Printed circuit board: Copper foil area of 1 cm^2 or more, and the board thickness of 1.7 mm for the collector portion

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

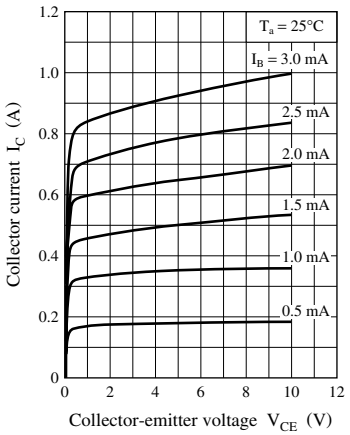
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	I_C = 10 µA, I_E = 0	10			V
Collector-emitter voltage (Base open)	V_{CEO}	I_C = 1 mA, I_B = 0	10			V
Emitter-base voltage (Collector open)	V_{EBO}	I_E = 10 µA, I_C = 0	7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	V_{CB} = 7 V, I_E = 0			1	µA
Forward current transfer ratio	h_{FE}	V_{CE} = 1 V, I_C = 400 mA	200		700	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	I_C = 1 A, I_B = 25 mA		0.17	0.25	V
Transition frequency	f_T	V_{CB} = 6 V, I_E = −50 mA, f = 200 MHz		190		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	V_{CB} = 10 V, I_E = 0, f = 1 MHz		50		pF
Forward voltage *	V_F	I_F = 500 mA			1.3	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. ∗: Applicable to the built-in diode.

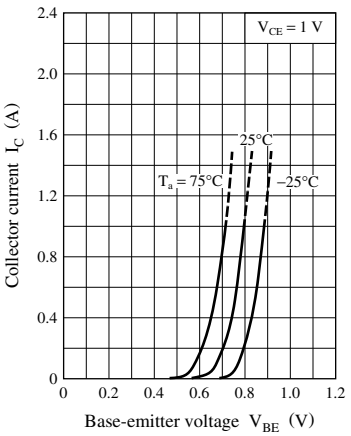
P_C — T_a



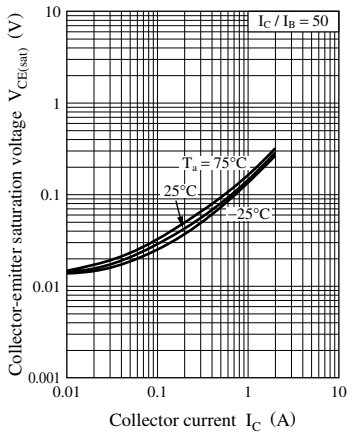
I_C — V_{CE}



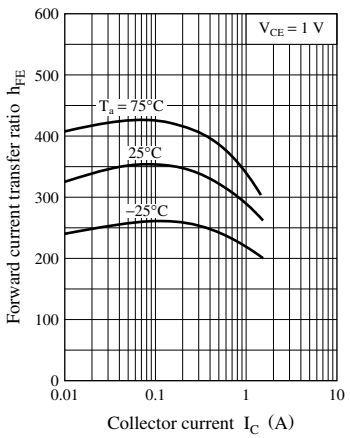
$V_{CE(sat)}$ — I_C



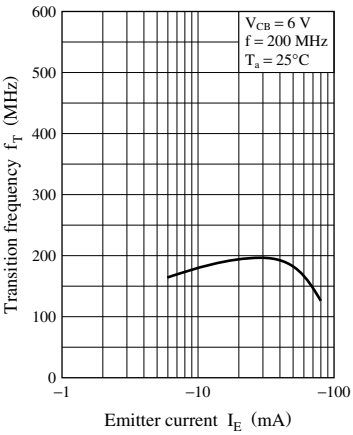
$V_{BE(sat)}$ — I_C



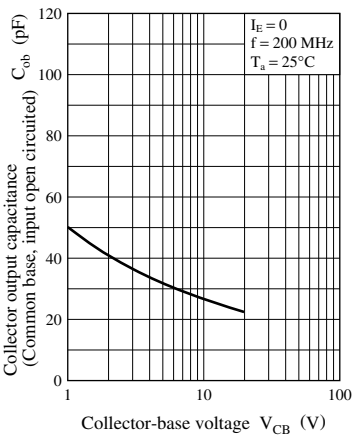
h_{FE} — I_C



f_T — I_E



C_{ob} — V_{CB}



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